





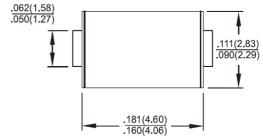
#### **Features**

- Glass passivated junction chip
- ♦ For surface mounted application
- ♦ Low profile package
- ♦ Built-in strain rellef
- ♦ Ideal for automated placement
- ♦ Easy pick and place
- ♦ Super fast recovery time for high efficiency
- ♦ Glass passivated chip junction
- → High temperature soldering: 260°C/10 seconds at terminals
- Plastic material used carries Underwriters Laboratory Classification 94V-0
- ♦ Green compound with suffix "G" on packing code & prefix "G" on datecode

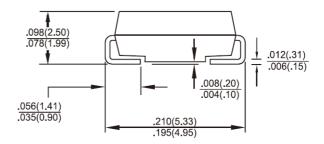
## **Mechanical Data**

- Cases: Molded plastic
- ♦ Terminals: Pure tin plated, lead free
- ♦ Polarity: Indicated by cathode band
- ♦ Packing: 12mm tape per EIA STD RS-481
- ♦ Weight: 0.064 grams

# SMA/DO-214AC



1.0AMP. Surface Mount Super Fast Rectifiers



## **Dimensions in inches and (millimeters)**

## **Marking Diagram**

ES1X SGYM ES1X = Specific Device Code G = Green Compound

Y = Year M = Work Month

# **Maximum Ratings and Electrical Characteristics**

Rating at 25  $^{\circ}$ C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	ES 1A	ES 1B	ES 1C	ES 1D	ES 1F	ES 1G	ES 1H	ES 1J	Units
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	150	200	300	400	500	600	V
Maximum RMS Voltage	$V_{RMS}$	35	70	105	140	210	280	350	420	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	150	200	300	400	500	600	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1								Α
Peak Forward Surge Current, 8.3 ms Single Half Sinewave Superimposed on Rated Load (JEDEC method)	I <sub>FSM</sub>	30								Α
Maximum Instantaneous Forward Voltage (Note 1) @ 1 A	V <sub>F</sub>	0.95			1.3		1	.7	V	
$ \begin{tabular}{lllllllllllllllllllllllllllllllllll$	I <sub>R</sub>	5 100								uA uA
Maximum Reverse Recovery Time (Note 2)	Trr	35								nS
Typical Junction Capacitance (Note 3)	Cj	16 18							pF	
Maximum Thermal Resistance	$R_{ heta JA} \ R_{ heta JL}$	85 35								°C/W
Operating Temperature Range	$T_J$	- 55 to + 150								οС
Storage Temperature Range	T <sub>STG</sub>	- 55 to + 150								οС

Note 1: Pulse Test with PW=300 usec, 1% Duty Cycle

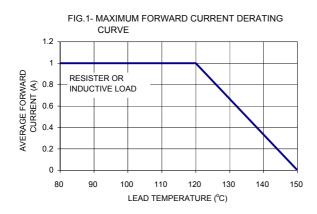
Note 2: Reverse Recovery Test Conditions:  $I_F$ =0.5A,  $I_R$ =1.0A,  $I_{RR}$ =0.25A

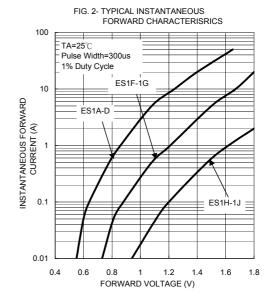
Note 3: Measured at 1 MHz and Applied  $V_R$ =4.0 Volts

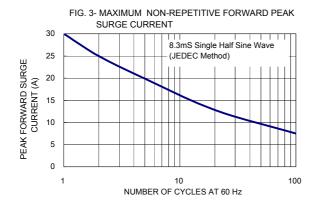
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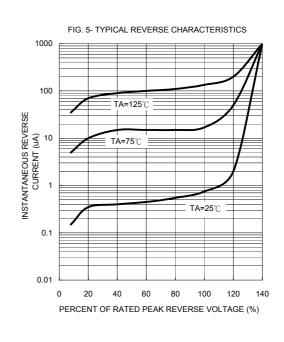


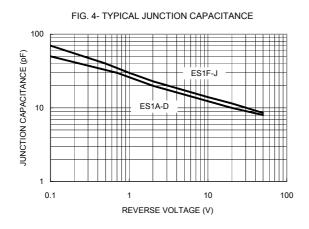
#### RATINGS AND CHARACTERISTIC CURVES (ES1A THRU ES1J)











### FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

